

cont.
 A3
 providing a circuit board comprising a main body, and a conductive layer provided on the main body, the conductive layer having a conductive pattern, the conductive pattern having at least one bonding area configured to correspond to the plurality of bumps of the part, the conductive layer having one of an isolated notch part and recess located proximate the at least one bonding area, wherein the notch part or the recess is configured to extend in a direction traverse to an ultrasonic vibrating direction of the ultrasonic bonding; and
 B
 subjecting the part and the circuit board to ultrasonic bonding in the ultrasonic vibrating direction.

11. The method as claimed in claim 10, wherein the notch part or the recess partially narrows the conductive pattern to form a narrow pattern part.

12. The method as claimed in claim 10, wherein the notch part or the recess narrows the conductive pattern at the at least one bonding area.--

IN THE ABSTRACT

Please delete the original Abstract and insert the following substitute Abstract of the Disclosure:

--ABSTRACT OF THE DISCLOSURE

A4
 A circuit board for mounting a part having a plurality of bumps by ultrasonic bonding. The circuit board includes a main body and a conductive layer provided on the main body. The conductive layer has a conductive pattern having at least one bonding area configured to correspond to the plurality of bumps of the part. The conductive layer has an isolated notch part located proximate the at least one bonding area.--